

LEAD TIMES

Standard Rigid:	10-15 days
Flex:	15 days
Multilayer Flex & Rigid-Flex:	20 days

24 turnaround available on request

TOLERANCES

DESIGN & TEST

Trace Tolerance	+ / - .0008"
Internal Drill to C _μ0075"
Pad Over FHS.....	.004"
Soldermask Clearance Over PAD Size004"
(Class 2: .005 / Class 3: .004)	
From C _μ to the Edge of the Board.....	.010"
Impedance.....	+ / - 10%

LAMINATION

Board Thickness	+ / - .010%
Layer to Layer Registration004"

DRILL & ROUT

Route.....	+ / - .005"
Inside Radius.....	.015"
Minimum Slot Width021"
Drill Positioning.....	+ / - .002"
From C _μ To The Edge of the Board010"
Impedance.....	+ / - 10%

CAPABILITIES

DESIGN & TEST

- 2 mil Trace Width
- 3 mil Air Gap
- IPC Class 2 / IPC Class 3 / 3 A
- Flying Probe Net List Test
- Differential Impedance
- TDR Testing
- Automatic Optical Inspection

LAMINATION

- 1 to 30 Layers
- Vacuum Lamination
- Sequential Lamination

DRILL & ROUT

- Counter Sinks / Counter Bores
- Scoring / Rout & Retain
- Laser Route
- Blind Vias / Buried Vias
- Stacked Vias

MATERIALS

- Flex and Rigid-Flex
- Kapton & Non-Kapton
- RF and High Speed Materials
- Mix Materials / FR-4 Teflon

- Metal Back Boards
(LED / Power Distribution)
- Heavy C_μ 6 oz. Finish Rigid and Rigid-Fle
(Stablecor)

CERTIFICATIONS

- UL ISO / AS 9100 C
- MIL-SPEC 31032 / 1B & 31032 / 4A
- ITAR
- IPC
- ODB++

PLATE

- Conductive Via Fill
Cu Plate Via Fill (micro vias)
- Non-Conductive Via Fill
- Plated Edges
- Plated Radii (Castellation)
- Hard Gold Body / Soft Bondable Gold
- Immersion Gold
(ENEPIG)
- HAL Lead Free (RoHS)
- HAL Standard
- Immersion Silver
- Entek (OSP)